

IN THE SPECIFICATION:

Please amend the specification as follows:

Please amend paragraph number [0054] as follows:

**[0054]** Where the polymeric layer 38 is a thermoplastic, the bus 40 may be attached to the polymeric layer 38 by heating the wire and pressing it into the polymeric layer 38. As shown in drawing FIG. 6, the wire 40E may have a shape which includes a lock 50 which is embedded in the polymeric layer 38 for firmly attaching the bus to the polymeric layer 38. The wire 40E may be heated by passing an electric current through the wire.

Please amend paragraph number [0059] as follows:

**[0059]** As depicted in drawing FIGS. 7 and 8, the connector 36 may be formed as a semicontinuous tape 58 with transverse buses 40 attached to the polymeric layer 38, e.g., Kapton™ polyimide. The tape 58 may be pre-manufactured to provide the desired bus configurations, pitch 48 and tape widths 60 applicable to a manufacturer's product line. The tape 58 is cut to fit each multi-IC chip package. As shown, the tape 58 may be placed on a spool 62 for easy dispensing and use. Alternately, a flex-circuit having transverse buses 40 secured to an etched polymeric layer 38 exposing the buses 40 may be used.

Please amend paragraph number [0070] as follows:

**[0070]** In use, the cage 84 with attached flex PCB 92 and buses 90 is attached to the host circuit board 30 with adhesive and the bus lower ends 124 are soldered or otherwise attached to the conductive pads or leads 34 of the host circuit board 30. The primary packages 14 are then inserted and pushed downwardly within the cage 84 to form an exemplary stack 86, the outer leads 16 of each primary package 14 compressed slightly during the insertion step.